TEA RELEASES MANUAL FOR CUSTOMERS
APPLICATIONS MANUAL FOR THERMAL TEST CHIP

Santa Clara, California, December 14, 2010 – Thermal Engineering Associates announced today the availability of the TTC Applications Manual for customers using its thermal test wafers, arrays, and chips. The TTC family has a broad range of uses in thermal, stress, and other forms of test and measurement for semiconductors.

The TTC Applications Manual helps users of the TTC family of products to understand the operation, application and customization options offered by TEA. Topics include: 1) diode temperature sensing and accuracy, 2) heat flux generation and the use of metal film resistors, 3) interconnect differences between bumped and wire bond arrays and wafers, 4) calibration methods including absolute and differential measurements, 5) electrical connection issues and alternatives, 6) considerations in the analysis of results, and 7) backside metallization alternatives.

"The applications for our TTC family of products has become so extended," said TEA President, Bernie Siegal, "that I came to realize that a guide for customers was a necessity. I am hopeful that the TTC Applications Manual will address the more common issues experienced by our customers."

For a copy of the TTC Applications Manual, TEA customers should contact Bill Ribble at bribble@thermengr.net.

About Thermal Engineering Associates:
TEA and its president, Bernie Siegal, have been providing thermal test and measurement hardware, software, and consulting services since 1973. Siegal has been chairman of the JEDEC JC15 committee and is the principle author of many MILSTD 750 thermal test methods. All major semiconductor companies, packaging companies, and many system level OEMs have utilized TEA equipment and/or services during its long history. Siegal is a founding member of IEEE SEMI-THERM and has delivered numerous papers and articles on thermal testing, simulation, and evaluation methods and techniques and is frequently sought out as a lecturer and expert in the field. www.thermengr.net.

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